

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

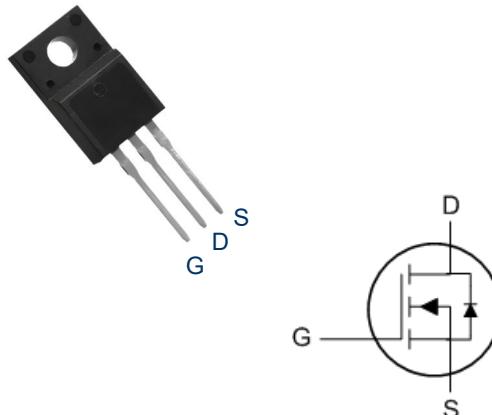
Product Summary

BVDSS	RDS(ON)	ID
40V	2.5mΩ	150A

Description

The XR150N04FT is the high performance complementary N-ch MOSFETs with high cell density, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XR150N04FT meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

TO220 Pin Configuration**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	150	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	85	A
I _{DM}	Pulsed Drain Current ²	560	A
EAS	Single Pulse Avalanche Energy ³	726	mJ
I _{AS}	Avalanche Current	---	A
P _D @T _C =25°C	Total Power Dissipation ⁴	115	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	---	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.3	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	---	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	2.5	3.1	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=20\text{A}$	---	3.5	4.7	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	1.0	1.7	2.5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	---	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=100^\circ\text{C}$	---	---	100	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=20\text{A}$	---	38	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	0.67	---	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	112	---	nC
Q_{gs}	Gate-Source Charge		---	16.7	---	
Q_{gd}	Gate-Drain Charge		---	26.5	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{GS}}=10\text{V}$, $V_{\text{DD}}=20\text{V}$, $R_G=3\Omega$, $I_D=10\text{A}$	---	18	---	ns
T_r	Rise Time		---	4.4	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	67	---	
T_f	Fall Time		---	9.5	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	6460	---	pF
C_{oss}	Output Capacitance		---	455	---	
C_{rss}	Reverse Transfer Capacitance		---	276	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	150	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

The data is tested by a surface mounted on a 1inch^2 FR-4 board with 2OZ copper.The data is tested by a pulsed pulse width $\leq 300\text{us}$ duty cycle $\leq 2\%$.The EAS data shows Max. rating. The test condition is $T_J=25^\circ\text{C}$, $V_{\text{DD}}=40\text{V}$, $V_{\text{G}}=10\text{V}$, $R_g=25\Omega$, $L=0.5\text{mH}$.The power dissipation is limited by 150°C junction temperature.The data is theoretically the same as A_{D} and A_{DMA} . In real applications, it should be limited by total power dissipation.

Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

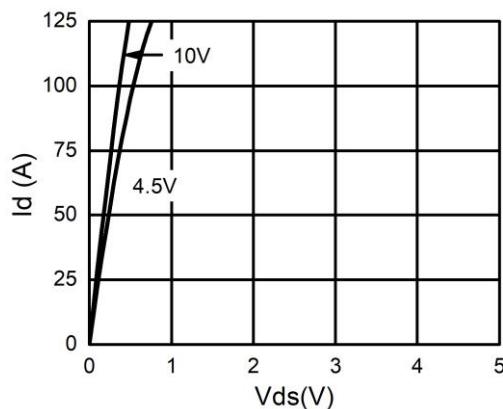


Figure 2. Transfer Characteristics

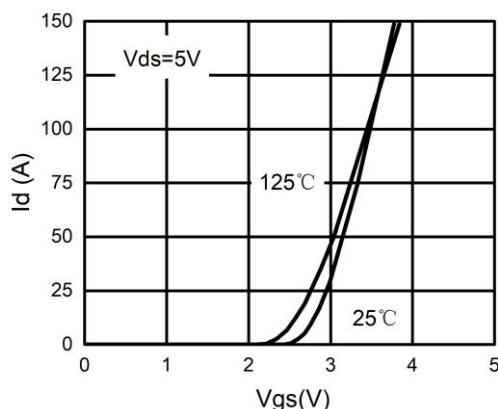


Figure 3. Power Dissipation

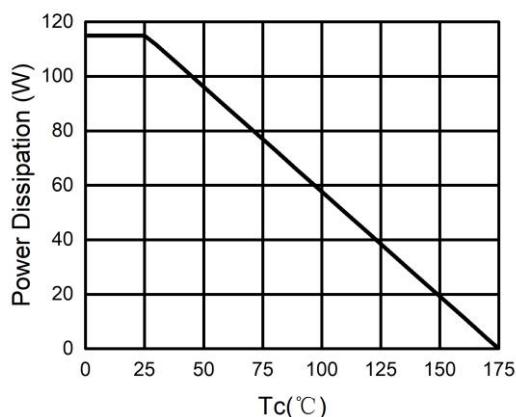


Figure 4. Drain Current

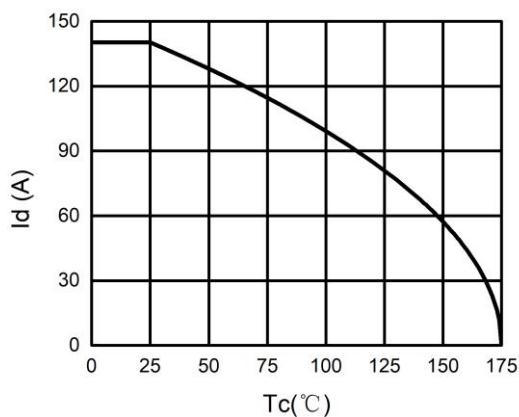


Figure 5. BV_{DSS} vs Junction Temperature

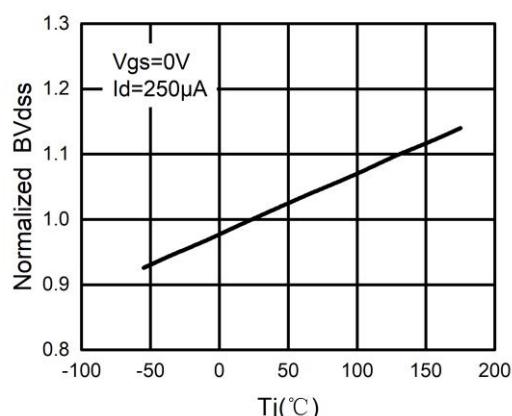


Figure 6. R_{DS(ON)} vs Junction Temperature

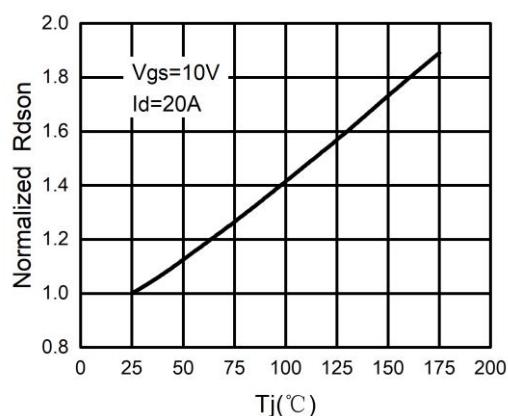
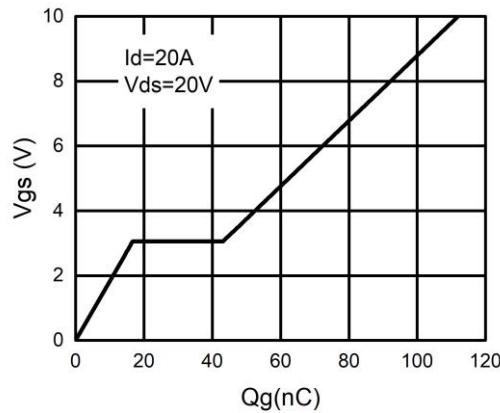
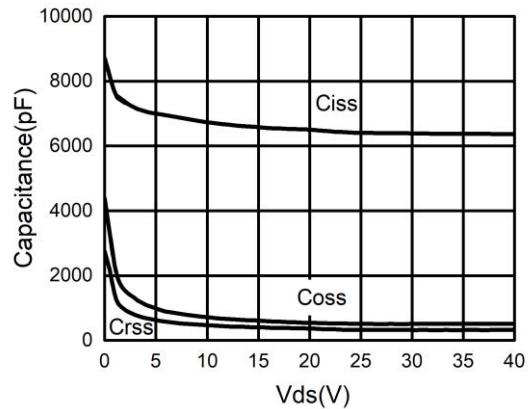
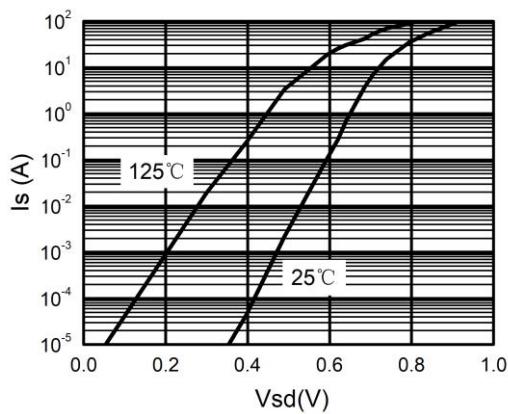
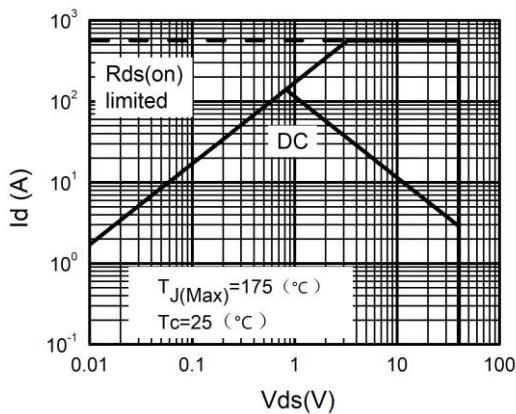
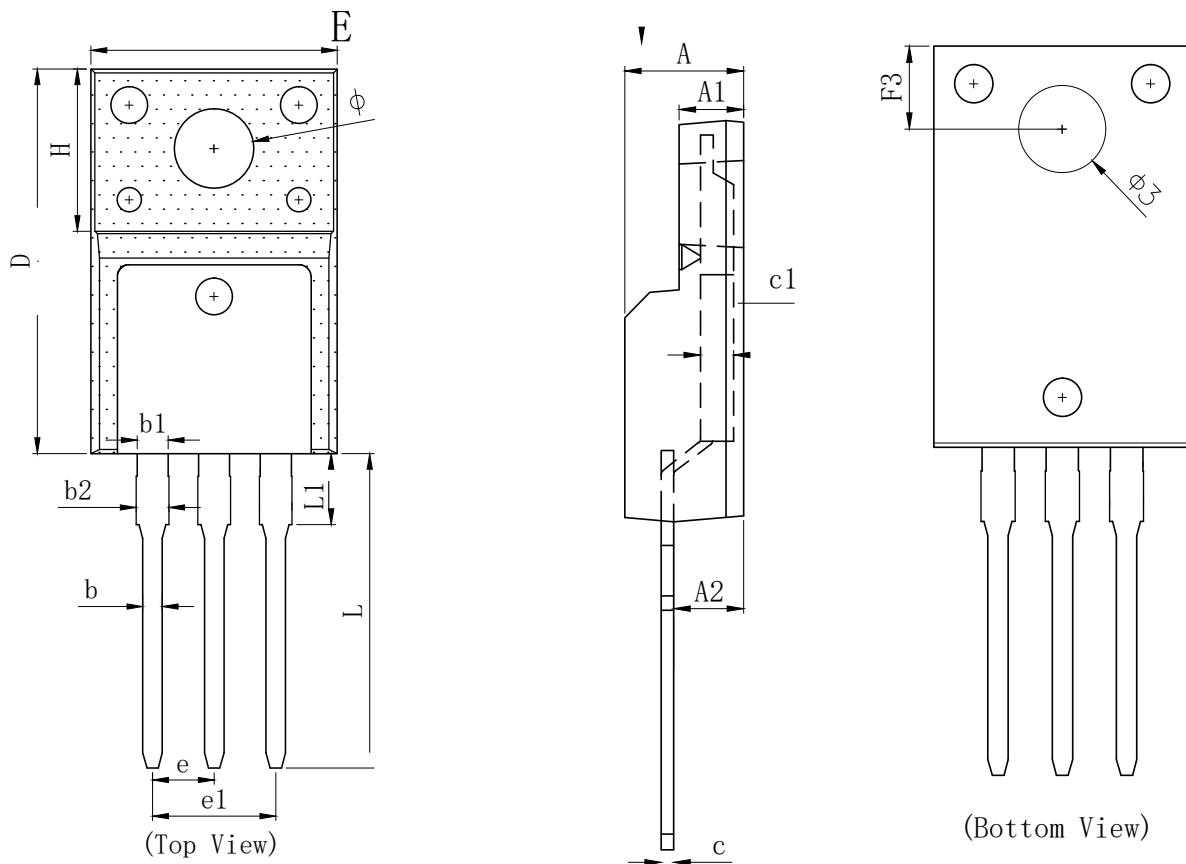


Figure 7. Gate Charge Waveforms**Figure 8. Capacitance****Figure 9. Body-Diode Characteristics****Figure 10. Maximum Safe Operating Area**

Mechanical Dimensions for TO-220F

SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	4.500	4.700	4.900
A1	2.340	2.540	2.740
A2	2.560	2.760	2.960
b	0.700	0.800	0.950
b1	1.180	1.280	1.430
b2	1.250	1.350	1.550
c	0.400	0.500	0.650
c1	1.200	1.300	1.350
D	15.570	15.870	16.170
H	6.700 REF		
E	9.960	10.160	10.360
e	2.540 BSC		
e1	5.080 BSC		
L	12.680	12.980	13.280
L1	2.780	2.930	3.080
F3	3.150	3.300	3.450
φ	3.030	3.180	3.450
φ 3	3.150	3.450	3.650